ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	al Composition De ht 2005. IPC, Bannock hal and Pan-American c	claration burn, Illinois. A opyright conver	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration he declaration er	on of the substan	ces within the manuf wer level materials f	acturer listed or which the	l item. Note: if manufacturer	the item is an as has engineering	sembly with low responsibility.	
759_91	IPC Web Site for Information on IPC-1752 Standard Form T			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				aterials and	ials and Mfg Information			
upplier Information													
ompany name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
nsemi									2023-06-08				
ontact Name	Title - Conta	Title - Contact			Phone - Contact*			Email	Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repres	Title - Representative			Phone - Representative*			Email	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA			Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	Version	Manufacturing Sit	e	Weight*	UOM	Unit Type	
	DF06M	DF06M BR MI		R MDIP PN 1.5A 600V		2023-06-08 PANJITF		PANJITFG		326.8213	mg	Each	
Ianufacturing Proccess I	nformation												
Terminal Plating / Grid	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperat		ature Max Time at I	Peak Temper	ature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		30	sec	onds 3			
omments													
or more information regarding	material composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part, the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.52	mg	А	Lead (Pb)	7439-92-1	7c	0.217	mg
			Supplier	Silicon (Si)	7440-21-3		4.2398	mg
			В	Nickel (Ni)	7440-02-0		0.0407	mg
			Supplier	Gold (Au)	7440-57-5		0.0226	mg
Die Attach Solder	9.8	mg	Supplier	Silver (Ag)	7440-22-4		0.245	mg
			А	Lead (Pb)	7439-92-1	7a	9.065	mg
			Supplier	Tin (Sn)	7440-31-5		0.49	mg
Lead Frame	116.12	mg	Supplier	Iron (Fe)	7439-89-6		0.1393	mg
			Supplier	Copper (Cu)	7440-50-8		115.9458	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0348	mg
Mold Compound-Black	195.3	mg		Metal Hydroxide	proprietary data		6.8355	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		15.624	mg
			Supplier	Carbon Black (C)	1333-86-4		0.9765	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		156.24	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		15.624	mg
Plating	1.0813	mg	Supplier	Tin (Sn)	7440-31-5		1.0813	mg